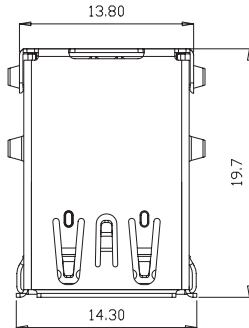
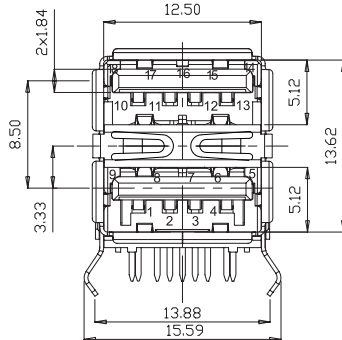
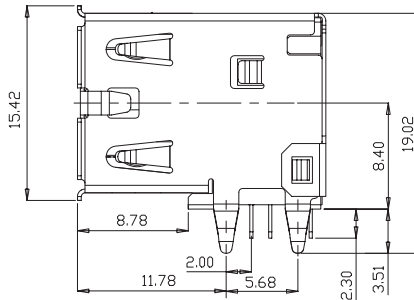
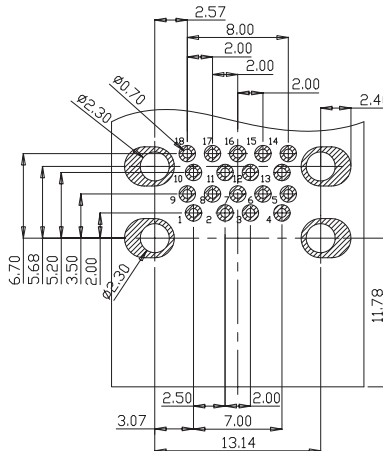

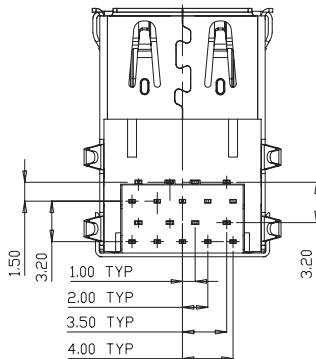
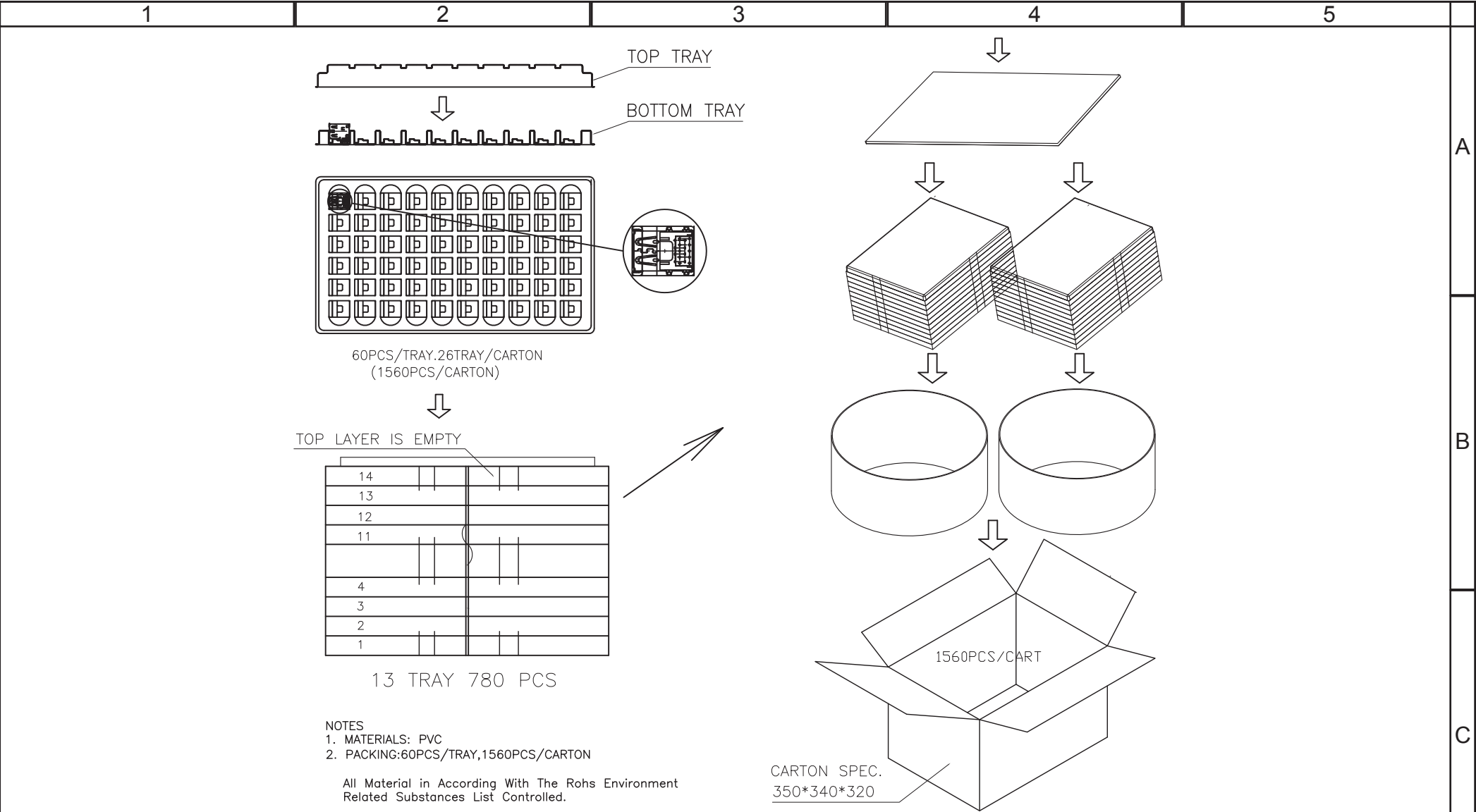
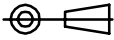

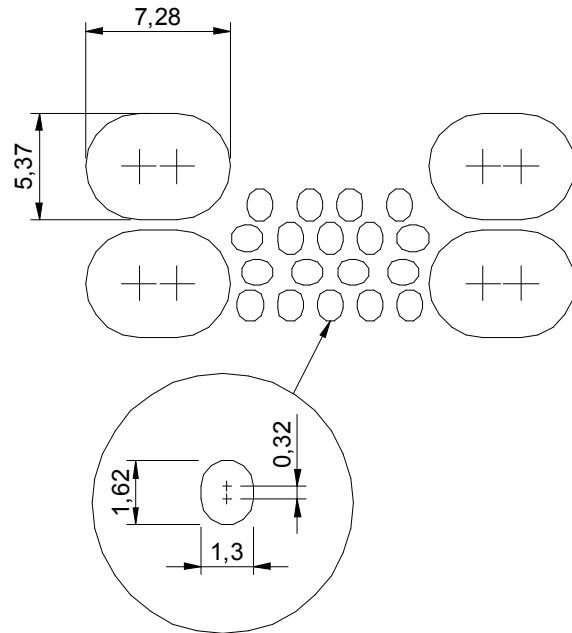


1				2				3				4				5			
																<div>TECHNICAL CHARACTERISTICS</div> <div>MATERIAL</div> <div>INSULATOR: LCP</div> <div>FLAMABILITY RATING: UL94-V0</div> <div>COLOR: BLUE</div> <div>CONTACT MATERIAL: PHOSPHORE BRONZE</div> <div>CONTACT TYPE: STAMPED</div> <div>CONTACT PLATING: UNDERPLATE 1.27 to 2.54 µm Ni</div> <div>CONTACT AREA 0.76 µm Gold</div> <div>SOLDER TAIL AREA 2.54 to 5.08 µm Matt Tin</div> <div>SHIELDING: BRASS MATT TIN PLATED</div> <div>ENVIRONMENTAL</div> <div>OPERATING TEMPERATURE: -20 up to +85°C</div> <div>COMPLIANCE: RoHS &amp; LEAD FREE AS PER DIRECTIVE 2002/95/EC</div> <div>HALOGEN FREE COMPLIANT AS PER IEC 61249-2-21</div> <div>ELECTRICAL</div> <div>CURRENT RATING:</div> <div>- PIN 1 &amp; PIN 4 (Vbus &amp; corresponding ground PIN) 1.8A Max</div> <div>- OTHER PINS 0.25 A Max</div> <div>WORKING VOLTAGE: 30Vac</div> <div>DIELECTRIC WITHSTANDING VOLTAGE: 100Vac/min</div> <div>INSULATION RESISTANCE: &gt; 100MΩ</div> <div>CONTACT RESISTANCE:</div> <div>- PIN 1 &amp; PIN 4: 30mΩ Max</div> <div>- OTHER PINS: 50mΩ Max</div> <div>STANDARD</div> <div> CERTIFIED: E323964 / MODEL NUMBER 692141030100</div> <div>MECHANICAL</div> <div>INSERTION FORCE: 35.0N Max</div> <div>EXTRACTION FORCE: 10.0N min</div> <div>QUALITY CLASS: 5000 MATING CYCLES</div> <div>SOLDERING</div> <div>WAVE &amp; REFLOW PROCESS AS PER JEDEC J-STD-020D</div> <div>PACKAGING</div> <div>TRAY</div>			
								PCB LAYOUT * - COMPONENT VIEW											



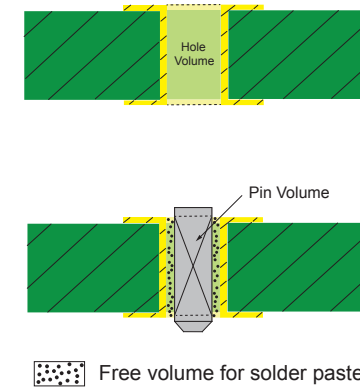
RoHS Compliant				PROJECTION: 	GENERAL TOLERANCE .X = +/- 0.2 .XX = +/- 0.15	 WÜRTH ELEKTRONIK	DESCRIPTION: USB 3.0 STACKED TYPE A	SIZE <b>A4</b>
G								
F								
E								
D								
C				APPROVAL: RJ	UNIT: MM	WERI PART NO: 692 141 030 100		
B					SCALE:			
A	02-APR-10	PROVISOIRE SHEET	JP		SHEET: 2/3			
REV	DATE	FILE	BY		DRAW: JOE			

# Stencil information for Through Hole Reflow soldering



STENCIL LAYOUT \* - COMPONENT VIEW



## PCB cross section



Theoretical Formula for Through Hole pins  
 Volume of the stencil aperture = (Hole volume - Pin volume) x 2  
 or  
 Volume of solder paste = (Hole volume - Pin volume) x 2

Stencil  
 Stencil Thickness: 150 µm

PCB  
 PCB thickness: 1.6mm

RoHS Compliant		* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS					
G				<div>PROJECTION:</div> <div></div>	<div>GENERAL TOLERANCE</div> <div>.X = <math>\pm</math> 0.2</div> <div>.XX = <math>\pm</math> 0.15</div>	<div></div>	
F							
E							
D							
C				APPROVAL: RJ	UNIT: MM	DESCRIPTION: USB 3.0 STACKED TYPE A	SIZE <b>A4</b>
B					SCALE:		
A					SHEET: 3/3	WERI PART NO: 692 141 030 100	
REV	DATE	FILE	BY		DRAW: JOE		